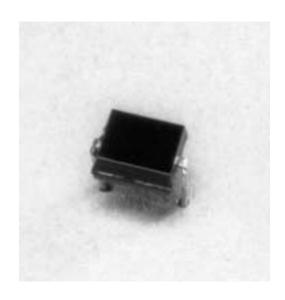
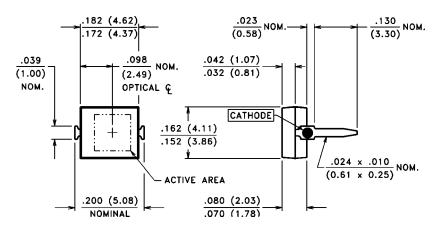
(BPW34F INDUSTRY EQUIVALENT)



PACKAGE DIMENSIONS inch (mm)



CASE 22 MINI DIP CHIP ACTIVE AREA: .012 in² (7.45 mm²)

PRODUCT DESCRIPTION

Planar silicon photodiode in a molded plastic package. The package material filters out visible light but passes infrared. Suitable for direct mounting to P.C.B. Arrays can be formed by positioning these devices side by side. The photodiodes are designed to provide excellent sensitivity at low levels of irradiance.

ABSOLUTE MAXIMUM RATINGS

Storage Temperature: -20°C to 80°C Operating Temperature: -20°C to 80°C

RoHS Compliant



ELECTRO-OPTICAL CHARACTERISTICS @ 25°C

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	VTD34FH			
			Min.	Тур.	Max.	UNITS
Re	Responsivity	0.5 mW/cm ² , 940 nm	15			μΑ
V _{OC}	Open Circuit Voltage	0.5 mW/cm ² , 940 nm	275	350		mV
TC V _{OC}	V _{OC} Temperature Coefficient	2850 K		-2.0		mV/°C
I _D	Dark Current	H = 0, V _R = 10 V		2	30	nA
C_J	Junction Capacitance	@ 1 MHz, V _R = 0 V		60		pF
t_R/t_F	Rise/Fall Time @ 1 kΩ Lead	V _R = 10 V, 833 nm		50		nsec
S _R	Sensitivity	@ Peak		0.60		A/W
λ_{range}	Spectral Application Range		725		1150	nm
$\lambda_{\rm p}$	Spectral Response - Peak			940		nm
V_{BR}	Breakdown Voltage		40			V
$\theta_{1/2}$	Angular Resp50% Resp. Pt.			±50		Degrees
NEP	Noise Equivalent Power		4.8 x 10 ⁻¹⁴			W∕√Hz
D*	Specific Detectivity			5.7 x 10 ¹²		cm√Hz/W

